

ABSTRACT OF THE DISCLOSURE

An interconnection substrate comprises an uppermost interconnection layer having a plurality of terminal pads located at positions corresponding to a plurality of solder bumps (external connection terminals) provided on a semiconductor element which is to be mounted on the interconnection substrate. The interconnection substrate also has a metal column formed on each of the terminal pads and has a resin film covering a side surface of the metal column. The interconnection substrate further has an insulating layer formed on the uppermost interconnection layer so that a gap is formed between the insulating layer and an outer peripheral surface of the resin film.